

SOT1094-1

plastic ball grid array package; 376 balls

8 February 2016

Package information

1. Package summary

| | |
|---------------------------------------|-----------------------|
| Terminal position code | B (bottom) |
| Package type descriptive code | BGA376 |
| Package type industry code | BGA376 |
| Package style descriptive code | BGA (ball grid array) |
| Package style suffix code | NA (not applicable) |
| Package body material type | P (plastic) |
| IEC package outline code | 144E |
| JEDEC package outline code | MS-034 |
| JEITA package outline code | - - - |
| Mounting method type | S (surface mount) |
| Issue date | 14-11-2008 |

Table 1. Package summary

| Symbol | Parameter | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|------|-----|------|------|------|
| D | package length | 26.8 | - | 27 | 27.2 | mm |
| E | package width | 26.8 | - | 27 | 27.2 | mm |
| A | seated height | 2 | - | 2.25 | 2.45 | mm |
| A ₂ | package height | 1.6 | - | 1.75 | 1.85 | mm |
| n ₂ | actual quantity of termination | - | - | 376 | - | |



2. Package outline

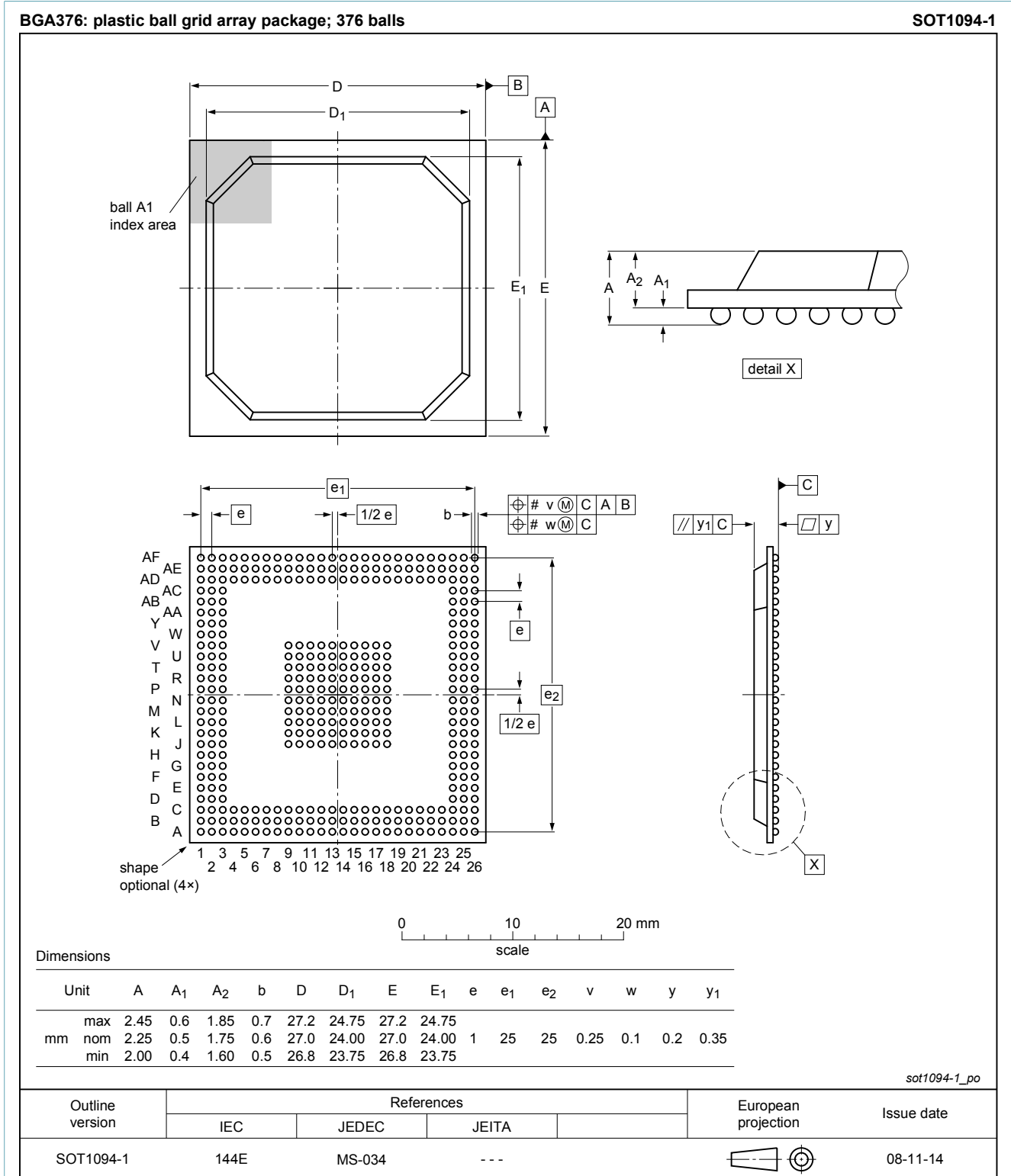


Fig. 1. Package outline BGA376 (SOT1094-1)

3. Legal information

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